

Littelfuse, Inc.
8755 West Higgins Road, Suite 500
Chicago, IL 60631 USA
(773) 628-1000

July 15th, 2025

PCN EIC-1153 Additional Epoxy Mold Compound Qualification for selected 8L DIP and SMT package type devices

Detailed Description of Change

Littelfuse IXYS Integrated Circuits Division (ICD) would like to inform you about the qualification of an additional EMC (Epoxy Mold Compound) to ensure security of supply for the part numbers summarized in the table below.

The affected part numbers listed below are fully qualified in accordance with established performance and reliability criteria.

Affected PN list		
LOC110	LOC110S	LOC110STR
LOC111	LOC111S	LOC111STR
LOC112	LOC112S	LOC112STR
LOC117	LOC117S	LOC117STR

Form, fit, function changes: None

Part number changes: None

Replacement products: N/A

Last time buy: N/A

Effective date: Immediately

The PCN number assigned to this action is **PCN EIC-1153** and must be referenced in any correspondence related to the change.

If you have any other questions or concerns, please contact your local Littelfuse sales representative or Product Manager below for further assistance.

Juste Valentiniene
Product Manager
Solid State Relays (SSR)
Tel: +370 (612) 49707
jvalentiniene@littelfuse.com